# DESCRIPTION

This device has been designed to meet the increasing demand for AlInGaP technology.

The package of the VLMF31.. is the PLCC-2.

It consists of a lead frame which is embedded in a white thermoplast. The reflector inside this package is filled up with clear epoxy.

# FEATURES

**High Intensity SMD LED** 

- SMD LED with exceptional brightness
- Luminous intensity categorized
- Compatible with automatic placement
  equipment
- EIA and ICE standard package
- Compatible with IR Reflow, vapor phase and wave solder processes acc. to CECC 00802 and J-STD-020C
- Available in 8 mm tape
- Low profile package
- Non-diffused lens: excellent for coupling to light pipes and backlighting
- Low power consumption
- Luminous intensity ratio in one packaging unit  $I_{Vmax}/I_{Vmin} \leq 1.6$
- Lead (Pb)-free device-RoHS compliant
- Preconditioning: acc. to JEDEC Level 2a
- ESD-withstand voltage: up to 2 kV according to JESD22-A114-B

# APPLICATIONS

- Automotive: Backlighting in dashboards and switches
- Telecommunication: Indicator and backlighting in telephone and fax
- Indicator and backlight for audio and video equipment
- · Indicator and backlight in office equipment
- Flat backlight for LCDs, switches and symbols
- General use

PARTS TABLE			
PART	COLOR, LUMINOUS INTENSITY	ANGLE OF HALF INTENSITY (± $\phi$ )	TECHNOLOGY
VLMF31Q2T1-GS08	Soft Orange, $I_V = (90 \text{ to } 355) \text{ mcd}$	60°	AllnGaP on GaAs
VLMF31Q2T1-GS18	Soft Orange, I <sub>V</sub> = (90 to 355) mcd	60°	AllnGaP on GaAs
VLMF31R1S2-GS08	Soft Orange, I <sub>V</sub> = (112 to 280) mcd	60°	AllnGaP on GaAs
VLMF31R1S2-GS18	Soft Orange, $I_V = (112 \text{ to } 280) \text{ mcd}$	60°	AllnGaP on GaAs
VLMF31S1T1-GS08	Soft Orange, I <sub>V</sub> = (180 to 355) mcd	60°	AllnGaP on GaAs
VLMF31S1T1-GS18	Soft Orange, I <sub>V</sub> = (180 to 355) mcd	60°	AllnGaP on GaAs





**Vishay Semiconductors** 

# Vishay Semiconductors



#### **ABSOLUTE MAXIMUM RATINGS<sup>1)</sup>, VLMF31..** TEST CONDITION PARAMETER SYMBOL VALUE UNIT Reverse voltage<sup>2)</sup> VR ٧ 5 $T_{amb} \le 85 \ ^{\circ}C$ DC Forward current $I_{F}$ 30 mA Surge forward current t<sub>p</sub> ≤ 10 μs IFSM 0.1 А Power dissipation $P_V$ 80 mW Τį Junction temperature 125 °C °C Operating temperature range Tamb - 40 to + 100 Storage temperature range T<sub>stg</sub> - 40 to + 100 °C Thermal resistance junction/ mounted on PC board 400 K/W R<sub>thJA</sub> ambient $(pad size > 16 mm^2)$

Note:

<sup>1)</sup>  $T_{amb} = 25 \degree C$  unless otherwise specified

<sup>2)</sup> Driving the LED in reverse direction is suitable for a short term application

OPTICAL AND ELECTRICAL CHARACTERISTICS <sup>1)</sup> , VLMF31, SOFT ORANGE							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN	TYP.	MAX	UNIT
Luminous intensity <sup>2)</sup>	I <sub>F</sub> = 20 mA	VLMF31Q2T1	Ι <sub>V</sub>	90		355	mcd
		VLMF31R1S2	Ι <sub>V</sub>	112		280	mcd
		VLMF31S1T1	Ι <sub>V</sub>	180		355	mcd
Dominant wavelength	I <sub>F</sub> = 20 mA		λ <sub>d</sub>	598	605	611	nm
Peak wavelength	I <sub>F</sub> = 20 mA		λ <sub>p</sub>		610		nm
Angle of half intensity	I <sub>F</sub> = 20 mA		φ		± 60		deg
Forward voltage	I <sub>F</sub> = 20 mA		V <sub>F</sub>		2.0	2.6	V
Reverse voltage	I <sub>R</sub> = 10 μA		V <sub>R</sub>	5			V
Junction capacitance	V <sub>R</sub> = 0, f = 1 MHz		Cj		15		pF

Note:

<sup>1)</sup>  $T_{amb} = 25 \degree C$  unless otherwise specified

<sup>2)</sup> in one Packing Unit  $I_{Vmax}/I_{Vmin} \le 1.6$ 

LUMINOUS INTENSITY CLASSIFICATION				
GROUP	LIGHT INTENSITY [MCD]			
STANDARD	OPTIONAL	MIN	MAX	
Р	1	45	56	
Г	2	56	71	
Q	1	71	90	
	2	90	112	
В	1	112	140	
n	2	140	180	
S	1	180	224	
5	2	224	280	
т	1	280	355	
	2	355	450	

#### Note:

Luminous intensity is tested at a current pulse duration of 25 ms and an accuracy of  $\pm$  11 %.

The above type numbers represent the order groups which include only a few brightness groups. Only one group will be shipped on each reel (there will be no mixing of two groups on each reel).

In order to ensure availability, single brightness groups will not be orderable.

In a similar manner for colors where wavelength groups are measured and binned, single wavelength groups will be shipped on any one reel. In order to ensure availability, single wavelength groups will not be orderable.

CROSSING TABLE		
VISHAY	OSRAM	
VLMF31Q2T1	LOT676-Q2T1	
VLMF31R1S2	LOT676-R1S2	
VLMF31S1T1	LOT676-S1T1	

# **COLOR CLASSIFICATION**

GROUP	SOFT ORANGE		
	DOM. WAVELENGTH (NM)		
	MIN.	MAX.	
1	598	601	
2	600	603	
3	602	605	
4	604	607	
5	606	609	
6	608	611	

#### Note:

Wavelengths are tested at a current pulse duration of 25 ms and an accuracy of  $\pm$  1 nm.



## **TYPICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified

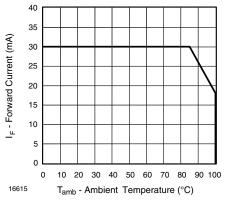
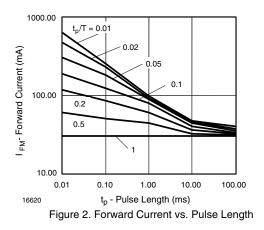


Figure 1. Forward Current vs. Ambient Temperature



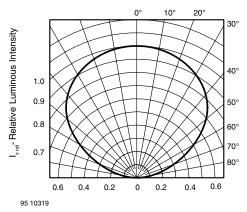
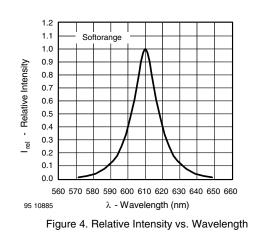
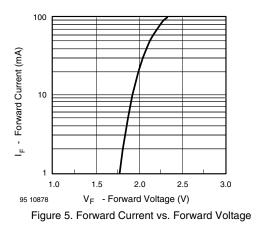


Figure 3. Rel. Luminous Intensity vs. Angular Displacement





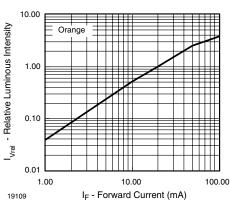


Figure 6. Relative Luminous Intensity vs. Forward Current

# VLMF31..

# Vishay Semiconductors



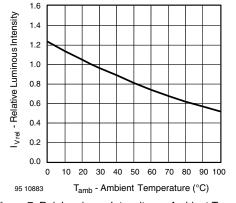


Figure 7. Rel. Luminous Intensity vs. Ambient Temperature

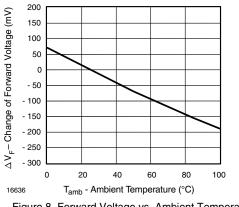
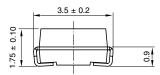
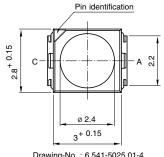


Figure 8. Forward Voltage vs. Ambient Temperature

## PACKAGE DIMENSIONS IN MM

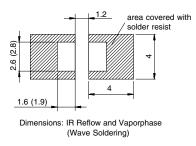




Drawing-No. : 6.541-5025.01-4 95 11314-1 Issue: 8; 22.11.05



Mounting Pad Layout

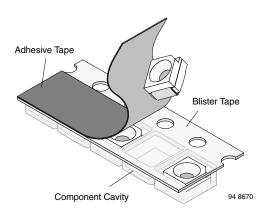




# METHOD OF TAPING/POLARITY AND TAPE AND REEL

## SMD LED (VLM3 - SERIES)

Vishay's LEDs in SMD packages are available in an antistatic 8 mm blister tape (in accordance with DIN IEC 40 (CO) 564) for automatic component insertion. The blister tape is a plastic strip with impressed component cavities, covered by a top tape.



### TAPING OF VLM.3..

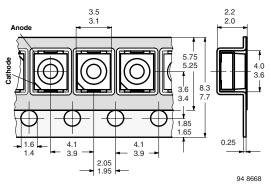


Figure 9. Tape dimensions in mm for PLCC-2

#### REEL PACKAGE DIMENSION IN MM FOR SMD LEDS, TAPE OPTION GS08 (= 1500 PCS.)

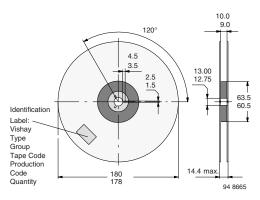


Figure 10. Reel dimensions - GS08

#### REEL PACKAGE DIMENSION IN MM FOR SMD LEDS, TAPE OPTION GS18 (= 8000 PCS.) PREFERED

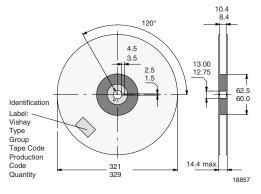
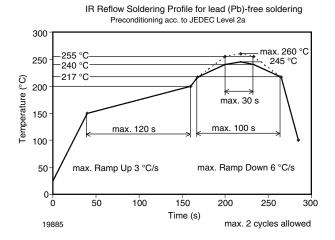


Figure 11. Reel dimensions - GS18





# SOLDERING PROFILE



#### Figure 12. Vishay Leadfree Reflow Soldering Profile (acc. to J-STD-020C)

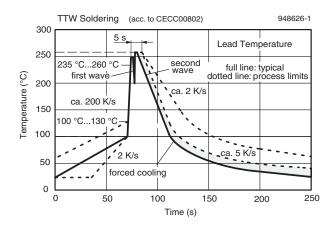
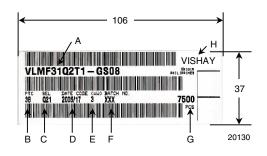


Figure 13. Double wave soldering of opto devices (all packages)

# BARCODE-PRODUCT-LABEL EXAMPLE:



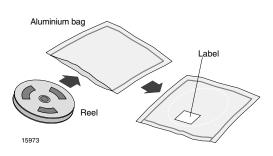
- A) Type of component
- B) Manufacturing Plant
- C) SEL Selection Code (Bin):
  e.g.: Q2 = Code for Luminous Intensity Group
  1 = Code for Color Group
- D) Date Code year/week
- E) Day Code (e.g. 3: Wednesday)
- F) Batch No.
- G) Total quantity
- H) Company Code

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# DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



# **FINAL PACKING**

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

# **RECOMMENDED METHOD OF STORAGE**

Dry box storage is recommended as soon as the aluminium bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity  $\leq$  60 % RH max.

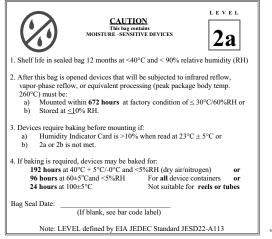
After more than 672 hours under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 hours at 40 °C + 5 °C/ - 0 °C and < 5 % RH (dry air/nitrogen) or

96 hours at 60  $^{\circ}\text{C}$  + 5  $^{\circ}\text{C}$  and < 5 % RH for all device containers or

24 hours at 100 °C + 5 °C not suitable for reel or tubes. An EIA JEDEC Standard JESD22-A112 Level 2a label is included on all dry bags.



Example of JESD22-A112 Level 2a label

# **ESD PRECAUTION**

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Antistatic Shielding Bag. Electro-Static Sensitive Devices warning labels are on the packaging.

## VISHAY SEMICONDUCTORS STANDARD BAR-CODE LABELS

The Vishay Semiconductors standard bar-code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.

# **Vishay Semiconductors**



# **OZONE DEPLETING SUBSTANCES POLICY STATEMENT**

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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